

US00D519087S

(12) United States Design Patent (10) Patent No.:

Hahn et al.

US D519,087 S

(45) Date of Patent: ** Apr. 18, 2006

MODULAR ELECTRONIC HOUSING AND **ASSEMBLIES**

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14 Years (**) Term:

Appl. No.: 29/233,209

Jun. 28, 2005 Filed: (22)

Related U.S. Application Data

(62)	Division	of	application	No.	29/195,922,	filed	on	Dec.	8,
	2003.								

(51)	LOC (8) Cl.	 13-03

U.S. Cl. D13/184

(52)(58)D14/240; 174/50, 52.1; 220/4.02; 361/600, 361/601, 679, 688, 704, 724, 796

See application file for complete search history.

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(57)**CLAIM**

The ornamental design for a modular electronic housing and assemblies, as shown and described.

DESCRIPTION

The modular electronic housing and assemblies thereof comprise an assembly of modular electronic housings intended to be used to house electronic circuit boards and their included electronic components.

The FIGURE is a right side perspective view of a modular electronic housing and assemblies showing our new design.

The broken line disclosure in the drawings are for illustrative purposes only and form no part of the claimed design.

1 Claim, 1 Drawing Sheet



